

- 16 (New) The module for an optical device as set forth in claim 1, wherein said patterning of said bonding portion is performed by affixing an adhesive sheet formed in a frame-like shape with substantially uniform thickness on said one side of said solid-state image sensor, or on the surface of said transparent cover opposite said one side of said solid-state image sensor.
- 17 (New) The module for an optical device as set forth in claim 16, wherein said transparent cover is formed to have a plane size smaller than the plane size of said one side of said solid-state image sensor.
- 18 (New) The module for an optical device as set forth in claim 17, comprising:  
an image processing device; and  
a wiring substrate, wherein  
said image processing device is bonded to said wiring substrate, and  
said solid-state image sensor is bonded to a plane portion of said image processing device.
19. (New) The module for an optical device as set forth in claim 1, wherein said patterning of said bonding portion is performed by coating a bonding agent with use of dispense method in a frame-like shape with substantially uniform thickness on said one side of said solid-state image sensor, or on the surface of said transparent cover opposite said one side of said solid-state image sensor.